Board Characteristics

0. All dimensions are given in inches unless specified otherwise.
2. Minimum trace width and clearance: 0.006".
3. 2 oz copper for all power layers and 1 oz copper for Signal_1,4 (Top and Bottom).
4. 1/2 oz copper for Stripling trace layers (Signal_2,3).
5. Immersion Gold over copper, with min. Ni: 3-7 um; Au: 0.05-0.12 um.

Applicable Mask over bare copper.

6. FMS tolerances: +/- 0.003 unless specified otherwise.
7. Interlayer spacing as specified.
8. This is a pressfit technology thru hole with the following specs:
   12-1. Finished plated hole size: 1.00 - 1.10 mm.
   12-2. Drilled hole size: 1.10 mm +/- 0.02mm
   12-3. Min. Thickness of thru hole plating: Cu: 25 um; Ni: 3-7 um; Au: 0.05-0.12 um.
9. Zc=55 Ohm +/- 10%; Zcuff = 110 +/- 10%.

Perforate TDR test for all signal layers.
Present TDR test results for all signal layers.

BOARD'S DRILL SCHEDULE

<table>
<thead>
<tr>
<th>DRILL SYMBOL</th>
<th>DRILL SIZE</th>
<th>COUNT</th>
<th>PLATED</th>
<th>TOLERANCE</th>
<th>COMMENT</th>
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<td>H</td>
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UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP
QUIET - EB Backplane Specification Drawing

SPECIFICATION

APPENDIX: DATE
INCHES
FRONT M. Resig / 6/29
BACK M. Resig / 6/29
SHEET
SIZE: 1:2